Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2551

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

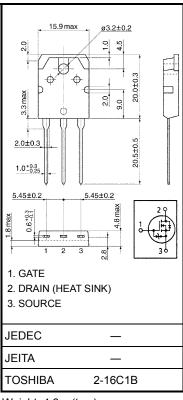
 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : \text{RDS (ON)} = 7.2 \text{ m}\Omega \text{ (typ.)} \\ \bullet & \text{High forward transfer admittance} & : | \text{Y}_{\text{fs}}| = 50 \text{ S (typ.)} \\ \end{array}$ 

• Low leakage current :  $I_{DSS} = 100 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = 50 \,\text{V})$ 

• Enhancement mode :  $V_{th} = 1.5 \sim 3.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	50	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	50	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	50	Α	
	Pulse (Note 1)	I <sub>DP</sub>	200	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	150	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	894	mJ	
Avalanche current		I <sub>AR</sub>	50	Α	
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 25 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial),  $L = 440 \mu\text{H}$ ,  $R_G = 25 \Omega$ ,  $I_{AR} = 50 \text{ A}$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

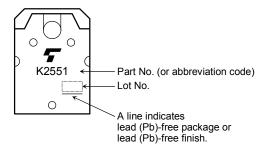
## Electrical Characteristics (Ta = 25°C)

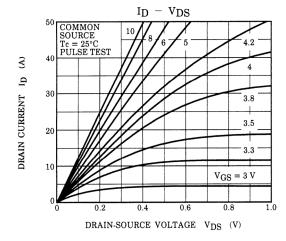
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	50	_	_	V
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A	_	7.2	11	mΩ
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 25 A	30	50	_	S
Input capacitano	ce	C <sub>iss</sub>		_	4000	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		800	_	pF
Output capacitance		Coss		_	2000	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{_{0 \text{ V}}} \stackrel{\text{I}_{D} = 25 \text{ A}}{_{0 \text{ V}}} \stackrel{\text{V}_{out}}{_{0 \text{ V}}} \stackrel{\text{R}_{L} = 1.2 \Omega}{_{0 \text{ V}}}$	_	25	_	
	Turn-on time	t <sub>on</sub>		_	40	_	ns ns
	Fall time	t <sub>f</sub>		_	120	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10 \mu \rm s$	_	360	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	130	_	nC
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 40 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$	_	90	_	
Gate-drain ("miller") charge		Q <sub>gd</sub>	]		40		

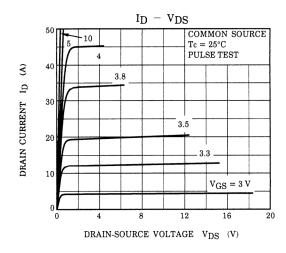
## Source-Drain Ratings and Characteristics (Ta = 25°C)

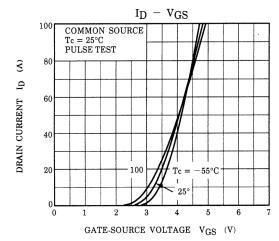
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	50	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	200	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 50 A, V <sub>GS</sub> = 0 V			-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 50 A, V <sub>GS</sub> = 0 V	1	140	_	ns
Reverse recovered charge	Qrr	dI <sub>DR</sub> / dt = 50 Å / μs	_	77	_	μC

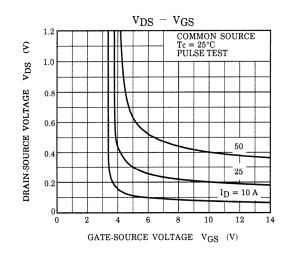
### Marking

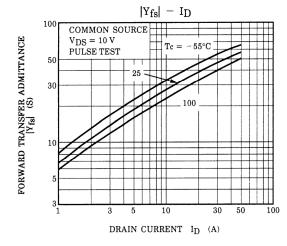


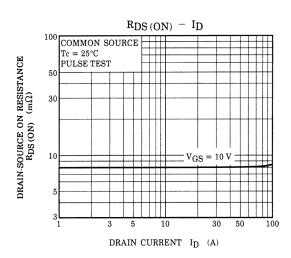


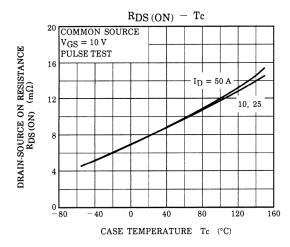


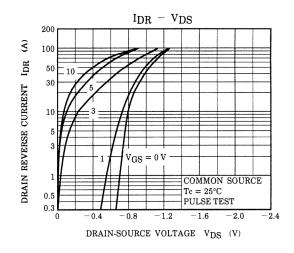


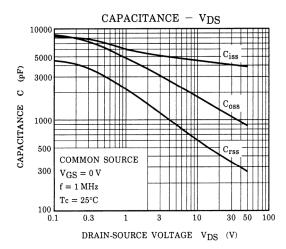


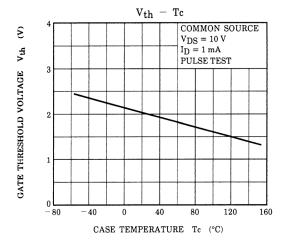


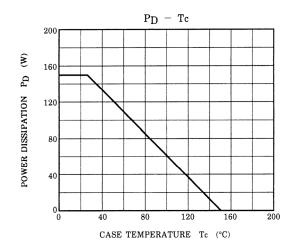


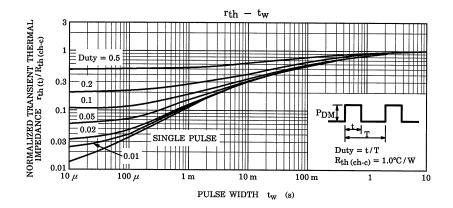


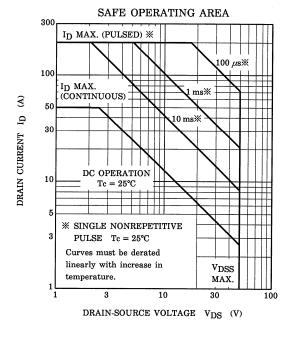


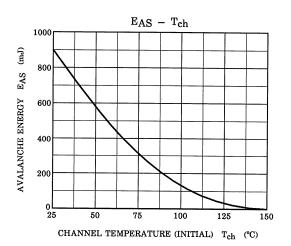


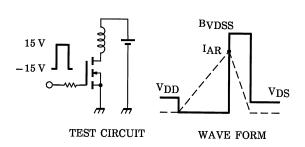












$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 25~V,~L = 440~\mu H \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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